NOV 1 2 1998 5 STATES PATENT AND TRADEMARK OFFICE

#3

Applicant:

Docket No.: TIS-25912

Fung Leng Chen, et al.

Examiner: Not Assigned

Serial No.: 09/115,444

RECEIVED

Art Unit: 2835

NOV 2 3 7001

Filing Date: 7/14/98

Title: High Density Internal Ball Grid Array Integrated Circuit Package

OFFICE OF PETITIONS

## PETITION FOR FILING UNDER 37 CFR 1.47 WHEN AN INVENTOR REFUSES TO SIGN OR CANNOT BE REACHED

Assistant Commissioner for Patents Washington, D.C. 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

Ting Rendon

Date

Enclosed please find a Declaration by Tina Rendon, Patent Secretary for Texas Instruments Incorporated, a copy of the cover letter sent to Salimah Hassan and the Declaration and Assignment signed by Fung Leng Chen and Chee Kiang Yew.

On September 8, 1998, the Declaration and Assignment forms, as filed with the subject application, and using the data set forth in the invention disclosure originally submitted by the inventors, were mailed to Salimah Hassan, secretary for Texas Instruments Singapore (PTE) Ltd.

TI Singapore has been unable to obtain the signature of Pang Hup Ong. Several attempts have been made by Texas Instruments Singapore to obtain his signature, but he has refused to sign the Declaration and Assignment.

TIS-25912 (Page 1)

Accordingly, application under 37 CFR 1.47 is hereby requested.

The last known address for Jing Sua Goh is listed on the attached Declaration and Assignment. Please charge the required fee under 37 CFR 1.17(h) to Deposit Account 20-0668 of Texas Instruments Incorporated.

Respectfully submitted,

Mark E. Courtney

Registration No. 36,491 Attorney for Applicants

Texas Instruments Incorporated P.O. Box 655474 M/S 3999 Dallas, TX 75265 (972) 278-9694 or (972) 917-5632



Texas Instruments Incorporated

Post Office Box 655474, M.S. 3999 Dallas, Texas 75265 7839 Churchill Way, M.S. 3999 Dallas, Texas 75251

(972) 917-5557 Fax: (972) 917-4418

-Fung teng Chen + Chee trong yew have both signed.

will mand Pang's cupy to you once he has Signed the document

8 September 1998

VIA FEDEX 8000 9023 0443

Salimah Hassan TEXAS INSTRUMENTS SINGAPORE (PTE) LIMITED 990 Bendemeer Road Singapore 339942

RE:

TIS-25912

New patent application in the United States Title: High Density Internal Ball Grid Array Integrated Circuit Package

Inventor(s): /Fung Leng Chen Chee Kiang Yew

Pang Hup Ong

Serial No:

09/115,444

Filed: 07/14/98

Dear Salimah:

Please arrange to have the enclosed Assignment and Declaration executed, as soon as conveniently possible and return to me by Express Mail no later than October 1, 1998. We have a deadline with the U.S. Patent Office.

The Assignment must be executed before a witness by an officer of TIS and by the inventor(s).

I have also enclosed a copy of the U.S. application.

Please acknowledge safe receipt of these papers by telex and advise the AIRBILL number when you return them.

Very truly yours,

Mark E. Courtney

TI Patent Attorney

Enclosures:

Assignment & Declaration Specification, claims and drawings

CC:

Connie Scourten



Applicant: Fung Leng Chen, et al.

Docket No.: TIS-25912

Serial No.: 09/115,444

Examiner: Not Assigned

Filing Date: 07/14/98

Art Unit: 2835

Title: High Density Internal Ball Grid Array Integrated Circuit Package

## **DECLARATION OF TINA RENDON**

Assistant Commissioner for Patents Washington, D.C. 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

Gina Genden

11-6-9'8

Date

Dear Sir:

TINA RENDON declares as follows:

- (1) THAT she is a secretary to Mark Courtney, the attorney in the Texas Instruments Incorporated Legal Department who handling the above-referenced application;
- (2) THAT Pang Hup Ong is listed as a joint inventor with Fung Leng Chen and Chee Kiang Yew.
- (3) THAT on September 8, 1998, Tina mailed the Assignment and Declaration forms to Salimah Hassan, secretary for Texas Instruments Singapore, as evidenced by the attached cover letter;
- (4) THAT she has been advised by Salimah Hassan that Texas Instruments Singapore has been unable to obtain Mr. Ong's signature.

I declare under penalty of perjury that the above is true and correct.

11-6-98

Date

Tina Rendon